図面番号(DRAWING NO.) SJ100130

版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	10.Feb.2006	059307	CORRECTION OF ERROR IN WRITTING	E.MURANO	Y.YAHIRO	—	K.Hisatomi

DESIGNATION

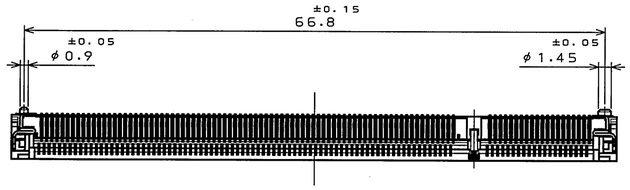
MM50-200B*-**RE

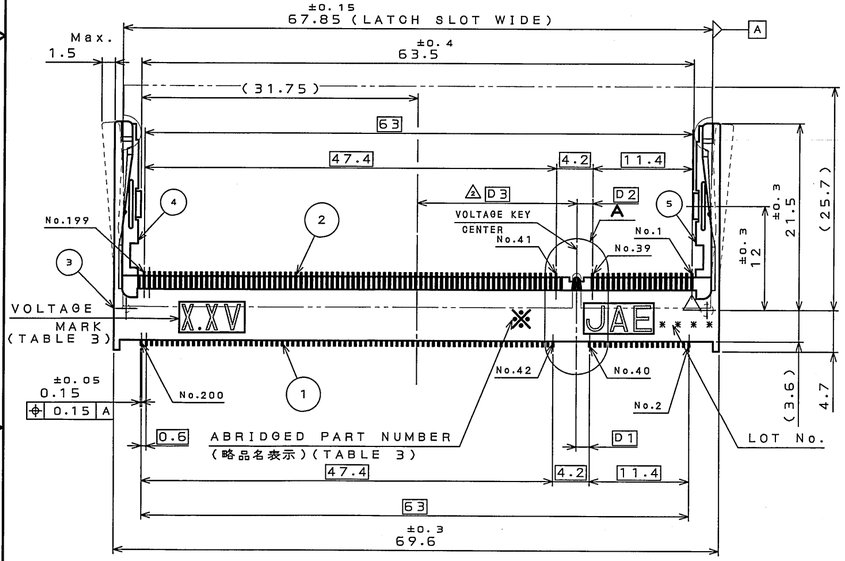
- SERIES PREFIX シリーズ名
- NO. OF CONTACTS 芯数
- SOCKET TYPE ソケットタイプ B:LATCH TYPE SMT
- KEYING TYPE(DETAIL A) キィタイプ 2:TYPE B(1.8V) 1:TYPE A(2.5V)
- CONTACT FINISH 接点仕上げ 1:Au(0.1μm MIN) OVER NI 2:Au(0.3μm MIN) OVER NI
- R :REVERSE NONE:STANDARD
- 錫または錫合金(無鉛) (LEAD FREE)TIN/TIN ALLOY

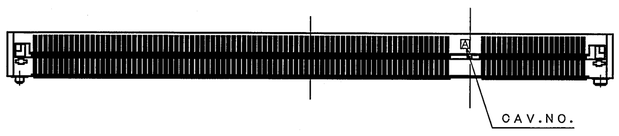
TABLE2

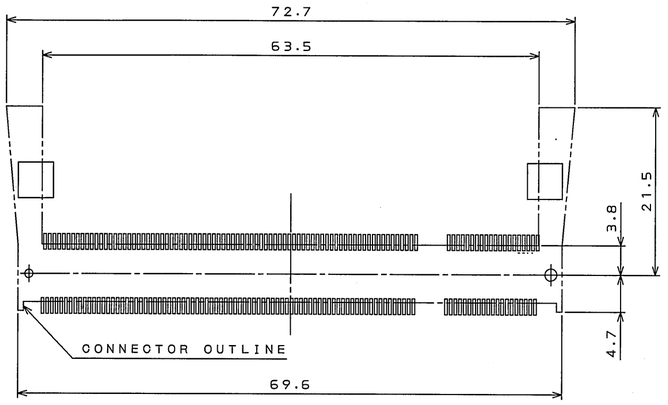
CONTACT FINISH

PARTS NAME	CONTACT AREA	SOLDERING AREA
MM50-200B*-1RE	Au(0.1μm Min.) OVER Ni	GOLD FLASH OVER Ni
MM50-200B*-2RE	Au(0.3μm Min.) OVER Ni	GOLD FLASH OVER Ni

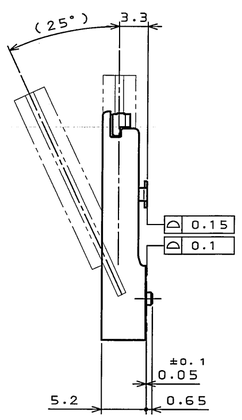








CONNECTOR MOUNTED AREA(REF.)



DETAIL A
(SCALE 5:1)
(REF.TABLE1)

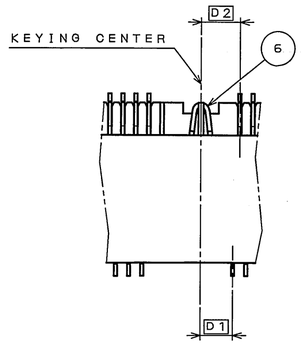
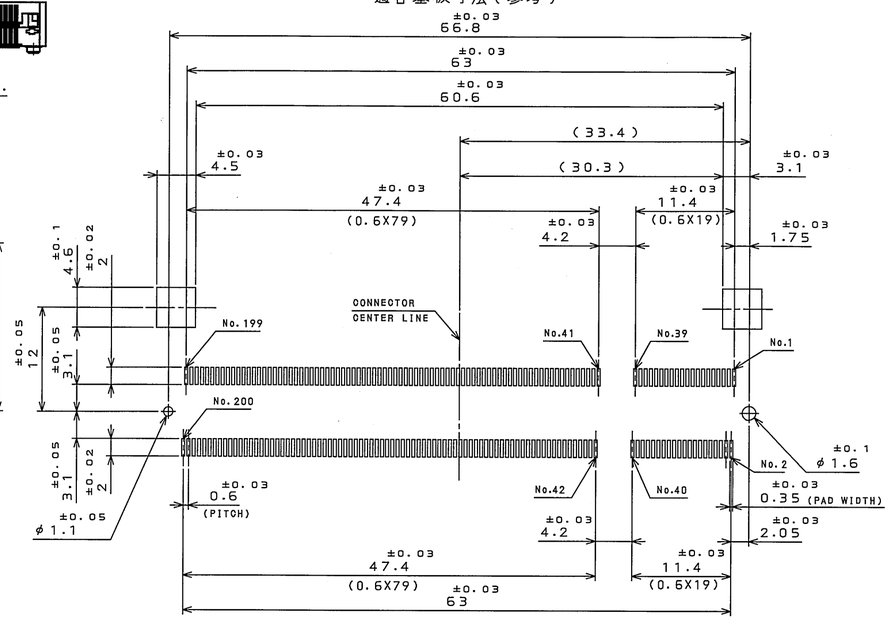


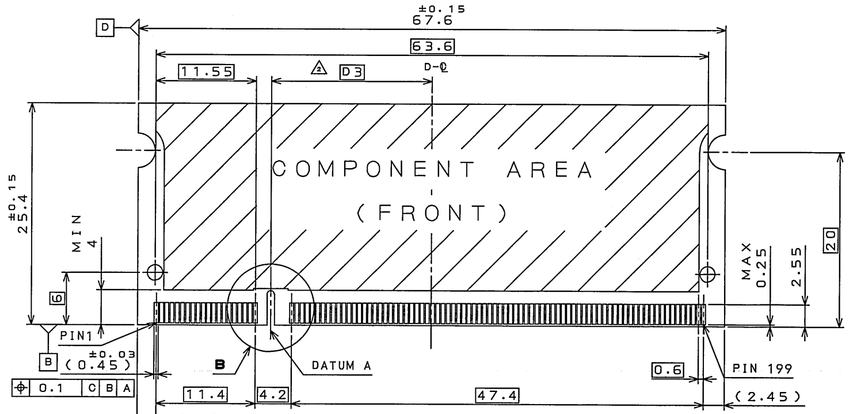
TABLE3

DISCRIMINATION MARK

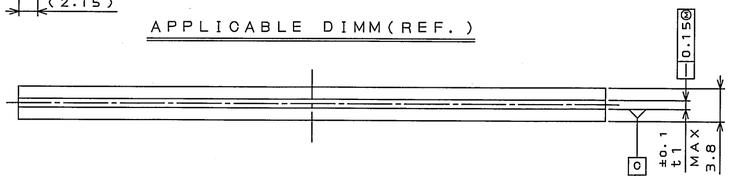
PARTS NAME	VOLTAGE MARK	ABRIDGED PART NUMBER
MM50-200B1-*RE	2.5V	*RE
MM50-200B2-*RE	1.8V	2-*RE

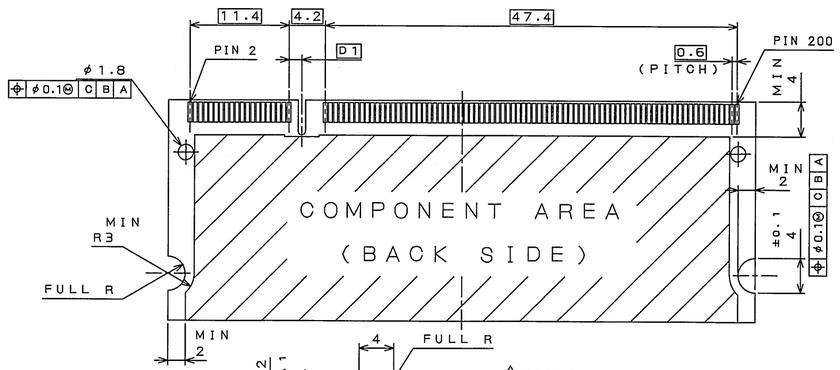
APPLICABLE P.C.B. DIMENSION(REF.)
適合基板寸法(参考)





APPLICABLE DIMM(REF.)





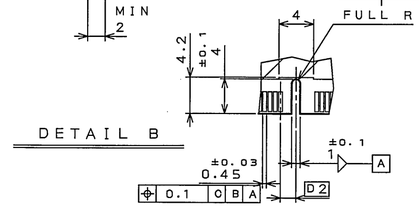


TABLE1

MECHANICAL KEYING

POWER SPPLY	D1	D2	D3
2.5V(TYPE A)	1.5	1.8	18.45
1.8V(TYPE B)	2.4	2.7	17.55

NO.	DESCRIPTION	QTY.	MATERIAL	FINISH	REMARKS
6	KEY	1	STAINLESS	—	—
5	HOLD DOWN 2	1	PHOSPHOR BRONZE	TIN PLATING	—
4	HOLD DOWN 1	1	PHOSPHOR BRONZE	TIN PLATING	—
3	INSULATOR	1	GLASS FILLED LCP	—	UL94 V-0 COLOR WHITE
2	BOTTOM SIDE CONTACT	100	PHOSPHOR BRONZE	SEE TABLE 2	—
1	TOP SIDE CONTACT	100	PHOSPHOR BRONZE	SEE TABLE 2	—

符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS

仕様書(SPECIFICATION)	JAOS-1655-01
一般公差(GENERAL TOLERANCE)	寸法(DIMENSION) ·±0.8 ·×±0.4 ·××±0.1 ·×××± 角度(ANGLES) ×°± ×'× '±
第1版(ORIGINAL DATE)	24.Oct.2003
製図 DR.	
担当 CHK.	R.KATOU
査閲 APPD.	Y.YAHIRO
承認 APPD.	S.KASHIWAGI
尺度(SCALE)	2:1
シリーズ(SERIES)	MM50
名称(TITLE)	MM50 -200B*-*RE
質量(MASS)	
日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.	
図面番号(DRAWING NO.)	SJ100130
版数(REV.)	2
SIZE	A2

JAE CONNECTOR.COM Reference Only

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